

## PROLABS – XFP-10GZR-OC192LR-C

*10 Gigabit 1550nm Single Mode XFP Optical Transceiver*

### XFP-10GZR-OC192LR-C Overview

PROLABS's XFP-10GZR-OC192LR-C 10 GBd XFP optical transceivers are designed for 10GBASE-ZR, 10GBASE-ZW, 10GFC and OC192 interconnects. The XFP-10GZR-OC192LR-C are compliant with the XFP Multi-Source Agreement (MSA) Specification. The Digital diagnostics functions are available via 2-wire serial interface, as specified in the XFP MSA.

### Product Features

- Up to 9.95 GBd to 11.1 GBd bit rates.
- Compliant with 10GBASE-ZR/ZW, 10GFC, OC192 application.
- Compliant with XFP MSA.
- Temperature-stabilized 1550nm EML laser.
- 30 pin XFP compatible connector.
- Standard bail mechanism for consistent installation and removal
- Built-in digital diagnostic functions.
- Hot Pluggable XFP footprint.
- Duplex LC Connectors.
- Up to 80km on SMF
- RoHS Compliance
- Class 1 laser product complies with EN 60825-1
- Operating temperature range: 0°C to 70°C

### Applications

- 10GBASE-ZR/ZW 10G Ethernet
- 80Km 10G Fiber Channel
- OC192 /STM-64

### Ordering Information

<b>Part Number</b>	<b>Description</b>
XFP-10GZR-OC192LR-C	OC-192/STM-64 LR 10GBASE-ZR XFP, 1550nm, 80km over SMF. DOM

## Absolute Maximum Ratings

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Storage Ambient Temperature	$T_S$	- 40		85	°C	
Supply Voltage 5V		- 0.5		5.5		
Supply Voltage 3.3V	$V_{CC\_3}$	- 0.5		4	V	

## General Specifications

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Data Rate	$DR$	9.95		11.1	GBd	
Bit Error Rate	$BER$			$10^{-12}$		
Total Power Consumption	$P$			3.5	W	
Supply Voltage - 5V	$V_{CC\_5}$	4.75		5.25	V	Operating Environment
Supply Voltage - 3.3V	$V_{CC\_3}$	3.13		3.45	V	Operating Environment
Supply Current - $V_{CC\_5}$ supply	$I_{CC\_5}$			350		
Supply Current - $V_{CC\_3}$ supply	$I_{CC\_3}$			500	mA	
Case Operating Temperature	$T_C$	0		70	°C	

## Link Distances

Parameter	Fiber Type	Distance Range (Km)
9.95 – 11.1 GBd	9/125um SMF	80

## Optical Characteristics - Transmitter

$V_{CC\_5}=4.75V$  to  $5.25V$ ,  $V_{CC\_3}=3.13V$  to  $3.45V$ ,  $T_C=0^{\circ}C$  to  $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Optical Wavelength	$\lambda$	1530		1570	nm	
Optical Power	$P_{OUT}$	0		4	dBm	Average
Launch Power of OFF Transmitter	$P_{OUT\_OFF}$			- 30	dBm	Average
Side Mode Suppression Ratio	$SMSR$	30			dB	
Optical Extinction Ratio	$ER$	8.2			dB	
Relative Intensity Noise	$RIN$			- 130	dB/Hz	
Transmitter Dispersion Penalty	$TDP$			2	dB	
Transmitter Jitter (Peak-to-Peak)	$T_j$			0.1	UI	

## Optical Characteristics - Receiver

$V_{CC\_5}=4.75V$  to  $5.25V$ ,  $V_{CC\_3}=3.13V$  to  $3.45V$ ,  $T_C=0^{\circ}C$  to  $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Center Wavelength Range	$\lambda_C$	1260		1600	nm	
Optical Input Power	$P_{IN}$			- 7	dBm	
Receiver Sensitivity in OMA @ 10.3Gb/s	$P_{SENS1}$			- 24	dBm	Measured with worst ER: $BER < 10^{-12}$ 2 <sup>31</sup> -1 PRBS
Receiver Reflectance	$TR_{RX}$			- 27	dB	
LOS De-Assert	$LOS_D$			- 30	dBm	
LOS Assert	$LOS_A$	- 35			dBm	
LOS Hysteresis		0.5			dB	

## Electrical Characteristics – Transmitter

$V_{CC5}=4.75V$  to  $5.25V$ ,  $V_{CC3}=3.13V$  to  $3.45V$ ,  $T_C=0^{\circ}C$  to  $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Input differential impedance	$R_{in}$		100		$\Omega$	After internal AC coupling
Differential data input swing	$V_{IN\_PP}$	120		820	mV	
Transmit Disable Voltage	$V_D$	2		$V_{CC}$	V	Or open circuit
Transmit Enable Voltage	$V_{EN}$	GND		GND+0.8	V	
Transmit Disable Assert Time				10	us	

## Electrical Characteristics – Receiver

$V_{CC5}=4.75V$  to  $5.25V$ ,  $V_{CC3}=3.13V$  to  $3.45V$ ,  $T_C=0^{\circ}C$  to  $70^{\circ}C$

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Differential data output swing	$V_{OUT\_PP}$	340	650	850	mV	
Data output rise time	$T_R$			38	ps	20%-80%
Data output fall time	$T_F$			38	ps	20%-80%
LOS Fault	$V_{LOS\_F}$	$V_{CC}-0.5$		$V_{CC\_HOST}$	V	
LOS Normal	$V_{LOS\_N}$	GND		GND+0.5	V	

## Digital Diagnostic

PROLABS's XFP-10GZR-OC192LR-C incorporates a XFP compliant 2-wire management interface which is used for serial ID, digital diagnostics, and certain control functions. It is modeled on the SFF-8472 Rev 9.3 specification modified to accommodate a single 2-wire interface address. In addition to the basic I<sup>2</sup>C read/write functionality the modules support packet error checking that, when enabled, allows the host system to confirm the validity of any read data. Details of the protocol and interface are explicitly described in the MSA. And the digital diagnostic functions via a 2-wire serial interface can provide real-time access to following operating parameters:

- Transceiver Temperature
- Laser Bias Current
- Transmitted Optical Power
- Received Optical Power
- Transceiver Supply Voltage

The block diagram illustrates the internal components of the optical subassembly. On the left, a vertical bus contains several input and control signals: TXDIS, TD+, TD-, MODNR, RD+, RD-, LOS, SDA, SCL, MODDESEL, and POWERDOWN. The TXDIS signal is connected to the LASER DRIVER. The TD+ and TD- signals are inputs to the TX CDR. The MODNR, RD+, RD-, and LOS signals are inputs to the RX CDR. The SDA, SCL, MODDESEL, and POWERDOWN signals are inputs to the MCU CONTROLLER. The TX CDR and RX CDR are stacked vertically. The RX CDR contains a LIMITING AMP block. The TX CDR is connected to the LASER DRIVER and SAFETY CONTROL block. The RX CDR is connected to the TIA AMP block. The LASER DRIVER and SAFETY CONTROL block is connected to the OPTICAL output. The TIA AMP block is connected to the RX\_MON signal. The MCU CONTROLLER is connected to the CDR\_SET, TX\_SET, and RX\_MON signals. The OPTICAL output is connected to the external network. The OPTICAL SUBASSEMBLY is shown as a dashed box containing the TIA AMP and the OPTICAL output.

The Laser Driver accept differential input data and provide bias and modulation currents for driving a laser. An automatic power control (APC) feedback loop is incorporated to maintain a constant average optical power. Laser in an eye safe optical subassembly (OSA) mates to the fiber cable. TX CDR is used to overcomes host board and connector signal degradations by reshaping, regenerating, and attenuating jitter.

TX DIS is a input pin. When TX DIS is asserted High, the XFP module transmitter output must be turned off.

The Receiver utilizes an APD detector integrated with a trans-impedance preamplifier in an OSA. The OSA is connected to a limiting Amplifier which providing post-amplification quantization, and optical signal detection. The limiting amplifier is AC coupled to the Trans-impedance amplifier , with internal 100ohm differential termination. RX CDR is used to overcomes host board degradations by reshaping, regenerating, and attenuating jitter.

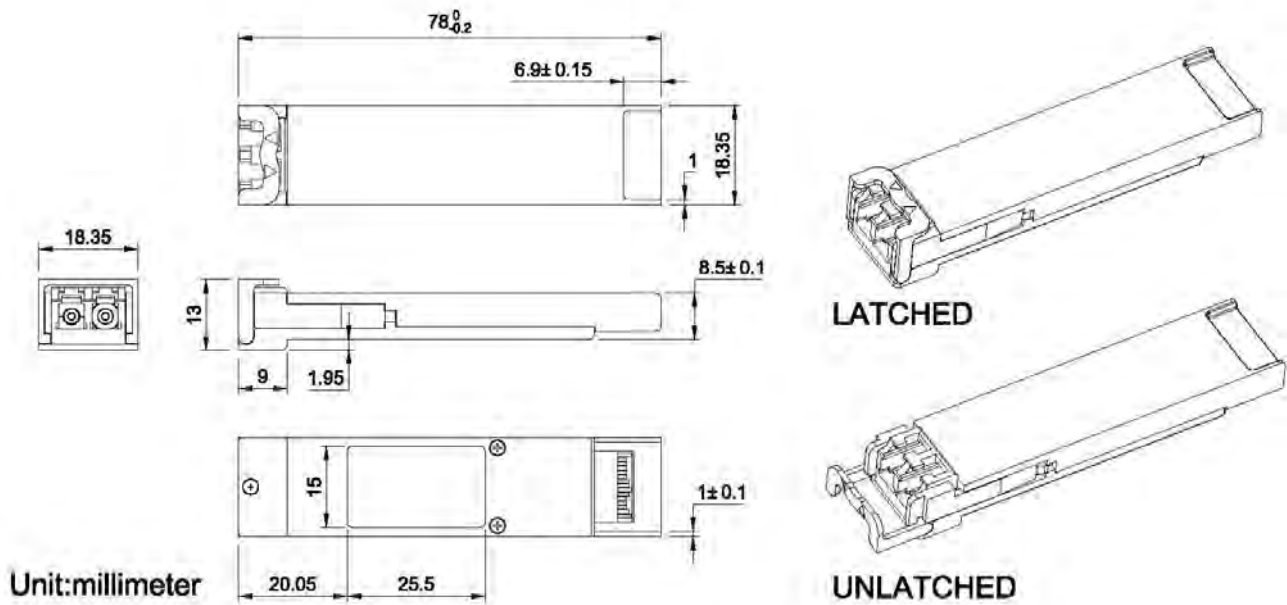
The LOS of an output pin, when LOS is high, it indicates insufficient optical power for reliable signal reception.

The MODNR is an output pin that when High, indicates that the module has detected a condition that renders transmitter and or receiver data invalid, shall consist of logical OR of the following signals:

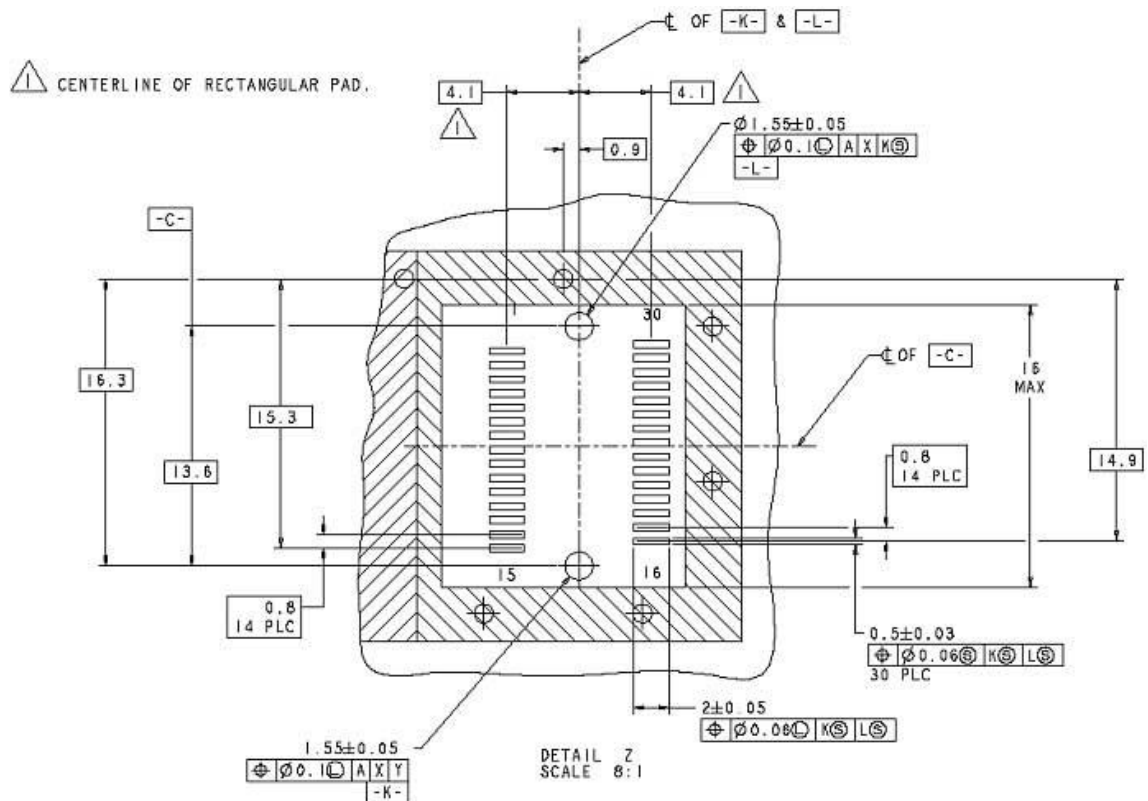
- ## Controller Section

The micro controller unit initializes the control register of laser driver, limiting amplifier and CDR. And monitors the running information from the laser driver, limiting amplifier and CDR. Then report these information to the customer.

## Dimensions



ALL DIMENSIONS ARE  $\pm 0.2\text{mm}$  UNLESS OTHERWISE SPECIFIED

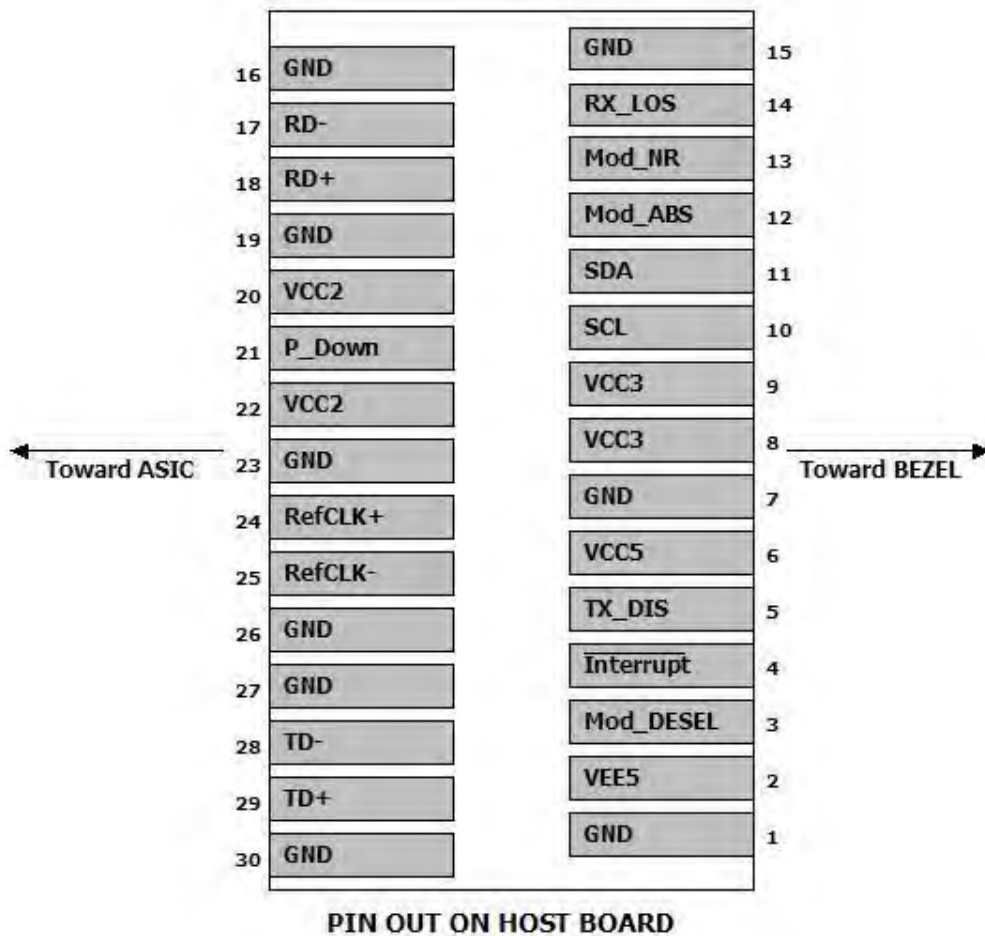




## Pin Assignment

PIN #	Symbol	Logic	Description	Remarks
1	GND		Module Ground	Module ground pins (GND) are isolated from the module case and chassis ground within the module
2	VEE5		Optional – 5.2 Power Supply (Not required)	
3	Mod-Desel	LVTTL-I	Module De-select, when held low allows the module to respond to 2-wire serial interface commands	
4	Interrupt	LVTTL-O	Indicates presence of an important condition which can be read over the serial 2-wire interface	Open collector, should be pulled up with 4.7kΩ-10kΩ on host board to a voltage between 3.15V and 3.6V
5	TX_DIS	LVTTL-I	Transmitter Disable, Transmitter laser source turned off	
6	VCC5		+5V Power Supply	
7	GND		Module Ground	Same as Pin# 1
8	VCC3		+3.3V Power Supply	
9	VCC3		+3.3V Power Supply	
10	SCL	LVTTL-I	Serial 2-wire interface clock	Same as Pin# 4
11	SDA	LVTTL-I/O	Serial 2-wire interface data line	Same as Pin# 4
12	Mod_Abs	LVTTL-O	Module Absent, Indicates module is not present. Grounded in the module	Same as Pin# 4
13	Mod_NR	LVTTL-O	Module Not Ready, Indicates Module operating fault	Same as Pin# 4
14	RX_LOS	LVTTL-O	Receiver Loss of Signal indicator	Same as Pin# 4
15	GND		Module Ground	Same as Pin# 1
16	GND		Module Ground	Same as Pin# 1
17	RD-	CML-O	Receiver inverted data output	
18	RD+	CML-O	Receiver non-inverted data output	
19	GND		Module Ground	Same as Pin# 1
20	VCC2		+1.8V Power Supply	
21	P_Down/RST	LVTTL-I	Power Down, When high, places the module in the low power stand-by mode and on the falling edge of P_Down initiates a module rest Reset, The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle	
22	VCC2		+1.8V Power Supply	
23	GND		Module Ground	Same as Pin# 1
24	RefCLK+	PECL-I	Reference Clock non-inverted input, AC coupled on the host board	
25	RefCLK-	PECL-I	Reference Clock inverted input, AC coupled on the host board	
26	GND		Module Ground	Same as Pin# 1
27	GND		Module Ground	Same as Pin# 1
28	TD-	CML-I	Transmitter inverted data input	
29	TD+	CML-I	Transmitter non-inverted data input	
30	GND		Module Ground	Same as Pin# 1

## Electrical Pad Layout



## References

1. 10 Gigabit Small Form Factor Pluggable Module (XFP) Multi-Source Agreement (MSA), Rev 4.5 – August 2005.